ATRON® AC 205

Aqueous-based defluxing agent for spray-in-air applications

ATRON® AC 205 is a FAST® (Fast Acting Surfactant Technology) Technology-based cleaning agent specifically designed to remove flux residues from electronic assemblies.

FAST® Technology cleaners such as ATRON® AC 205 are based on a new generation of surfactants with significantly enhanced characteristics. When compared to conventional surfactant-based cleaning agents, ATRON® AC 205 allows for much shorter contact times and provides a higher bath loading capacity. Therefore ATRON® AC 205 is especially suited for high pressure inline cleaning systems where short contact times are required.

Areas of application: **PCB cleaning**	
Low solid flux residues	++
Rosin-based flux residues	++
Water soluble flux residues	++
Solder paste (unsoldered)	+

++ highly recommended, best results + recommended 0 possible - not recommended

Further information on this product:

Technical Information 2:
Overview of all solder pastes tested

Technical Information 3:
Material compatibility overview

FAST® Technology:
Detailed information on FAST® Technology

Technical Centers - ① America, ② Europe, ③ Malaysia, ④ North-China, ⑤ South-China
Cleaning Process Solutions under Production Floor Conditions

Contact ZESTRON's Process Engineering Team for free-of-charge cleaning trials:
Phone: +49-841-635-26; Email: techsupport@zestron.com

Advantages compared to other surfactant cleaners:

- Free of Ethanolamine and other harmful substances.
- Allows for a quicker removal of a wide variety of the latest lead-free and eutectic flux residues.
- Longer bath life than conventional surfactant-based cleaners.
- Gentle formula leaves solder joints and pads shiny and bright.
- Specifically formulated for excellent compatibility with aluminum and epoxy surfaces.
- Low odor.
- Extremely low VOC value.

Please refer to the material compatibility list (Technical Information 3) before cleaning plastics.

TECHNICAL INFORMATION 1

Europe
Ingolstadt–Germany
info@zestron.com

America
Manassas, VA–USA
infousa@zestron.com

South Asia
Kulim–Malaysia
infoasia@zestron.com

North Asia
Shanghai/Shenzhen–China
infochina@zestron.com

Process Steps	1. Cleaning	2. Rinsing	3. Drying
Spray-in-air (inline)	ATRON® AC 205	Warm with DI-water (40°C/104°F)	Hot or circulating air
Spray-in-air (batch)	ATRON® AC 205	Warm with DI-water (40°C/104°F)	Hot or circulating air

[1] ATRON® AC 205 has to be diluted in DI-water.

Technical Data

Please note that this information represents ATRON® AC 205 at 10% concentration.

Density	g/ccm at 20°C/68°F	1.00
Surface tension	mN/m at 25°C/77°F	28.9
Boiling range	°C/°F	> 100 / 212
Flash point	°C/°F	None
pH-value	10g/l H_2O	10.4
Cleaning temperature	°C/°F	40 – 70 / 104 – 158
Application concentration[1] (inline)	%	5 – 15
Application concentration[1] (batch)	%	15 – 30
HMIS Rating	Health-Flammability-Reactivity	1 – 0 – 0

PRODUCT FEATURES

Extensively tested and suitable for cleaning of lead-free solder pastes

FAST® Technology ensures the fast removal of flux residues even under components

100% compliance with EU guidelines (RoHS 1 & 2, WEEE)

Product is free of any critical substances according to SIN & SVHC lists

Environmental, health and safety regulations

- ATRON® AC 205 is water-based and biodegradable.
- Refer to the MSDS for specific handling precautions and instructions.

Availability/Storage

- ATRON® AC 205 is available as a concentrate in 1l bottles, 5l or 25l containers and 200l drums.
- This product is hazardous.
- Store ATRON® AC 205 in the original container at a temperature between 5 - 30°C / 41- 86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.

Alternative product recommendation:

- For high end defluxing and closed loop processing requirements, we also recommend MPC® Technology-based products, such as VIGON® A 250 for low pressure batch cleaning and VIGON® A 201 for high and medium pressure inline cleaning.